

General Description

The Sanrise SRC65R024BS is a high voltage power MOSFET, fabricated using advanced super junction technology. The resulting device has extremely low on resistance, low gate charge and fast switching time, making it especially suitable for applications which require superior power density and outstanding efficiency.

The SRC65R024BS break down voltage is 650V and it has a high rugged avalanche characteristics. The SRC65R024BS is available in TO-247 package.

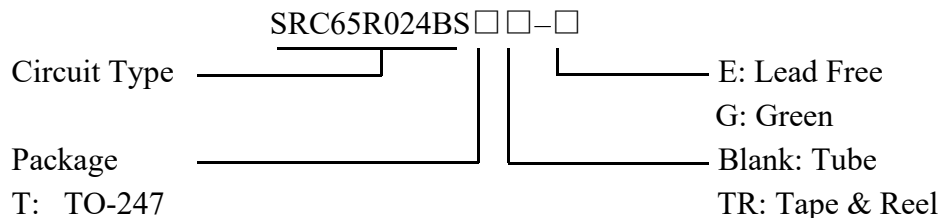
Features

- Ultra Low $R_{DS(ON)} = 24m\Omega @ V_{GS} = 10V$.
- Ultra Low Gate Charge, $Q_g=408nC$ typ.
- $V_{ds}@T_{jmax}=700v$.
- Intrinsic Fast-Recovery Body Diode
- Fast switching capability
- Robust design with better EAS performance
- Non-automotive Qualified
- Ultra-fast body diode

Application

- EV Charger
- Server / Telecom

Ordering Information



Symbol

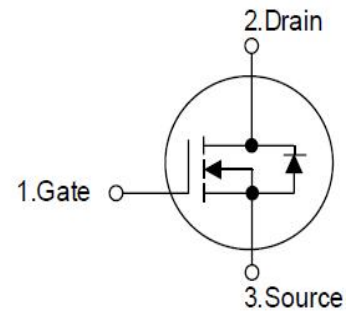


Figure 1 Symbol of SRC65R024BS

Package Type

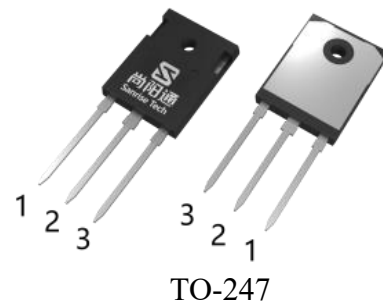


Figure 2 Package Type of SRC65R024BS

Package	Part Number	Marking ID	Packing Type
TO-247	SRC65R024BST-G	SRC65R024BSTG	Tube

Absolute Maximum Ratings^{Note 1}

Parameter		Symbol	Rating	Unit
Drain-Source Voltage		V_{DSS}	650	V
Gate-Source Voltage (static)		V_{GSS}	±20	V
Gate-Source Voltage (dynamic), AC ($f > 1$ Hz)		V_{GSS}	±30	V
Continuous Drain Current	$T_C = 25^\circ\text{C}$	I_D	110	A
	$T_C = 100^\circ\text{C}$		69	
	$T_C = 125^\circ\text{C}$		49	
Power Dissipation ($T_C = 25^\circ\text{C}, \text{TO-247}$)		P_{tot}	595	W
Pulsed Drain Current (Note 2)		I_{DM}	330	A
Avalanche Energy, Single Pulse (Note 3)		E_{AS}	413	mJ
Avalanche Energy, Single Pulse (Note 4)		E_{AS}	6000	mJ
Avalanche Energy, Repetitive (Note 2)		E_{AR}	0.4	mJ
Avalanche Current, Repetitive (Note 2)		I_{AR}	3.5	A
Continuous Diode Forward Current		I_S	110	A
Diode Pulse Current		$I_{S,PULSE}$	330	A
MOSFET dv/dt Ruggedness, $V_{DS} \leq 480\text{V}$		dv/dt	80	V/ns
Reverse Diode dv/dt , $V_{DS} \leq 480\text{V}, I_{SD} \leq I_D$		dv/dt	50	V/ns
Operating Junction Temperature		T_J	150	$^\circ\text{C}$
Storage Temperature		T_{STG}	-55 to 150	$^\circ\text{C}$
Lead Temperature (Soldering, 10 sec)		T_{LEAD}	260	$^\circ\text{C}$

Note:

- Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
- Repetitive Rating: Pulse width limited by maximum junction temperature
- $I_{AS} = 3.5\text{A}$, $V_{DD} = 60\text{V}$, $R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$. Finish goods test condition.
- $I_{AS} = 13.4\text{A}$, $V_{DD} = 60\text{V}$, $R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$. Typical Eas.

Thermal characteristics

Parameter (TO247-package)	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Case	R_{thJC}	-		0.21	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient	R_{thJA}	-		62	

Electrical Characteristics
 $T_J = 25^\circ\text{C}$, unless otherwise specified.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	650			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=650V, V_{GS}=0V$			10	μA
Gate-Body Leakage Current	Forward	$I_{GSSF}, V_{GS}=20V, V_{DS}=0V$			200	nA
	Reverse	$I_{GSSR}, V_{GS}=-20V, V_{DS}=0V$			-200	
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=2.9mA$	3.5	4.5	5.5	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=40A$		19	24	mΩ
Gate Resistance	R_G	f=1MHz, Open Drain		0.9		Ω
Dynamic Characteristics						
Input Capacitance	C_{ISS}	$V_{DS}=400V, V_{GS}=0V,$ f=100kHz		8.3		nF
Output Capacitance	C_{OSS}			208		pF
Effective output capacitance, energy related ^{NOTE5}	$C_{O(er)}$	$V_{GS}=0V,$ $V_{DS}=0\dots 400V$		316		pF
Effective output capacitance, time related ^{NOTE6}	$C_{O(tr)}$			1722		
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=400V, I_D=40A$ $R_G=3.0\Omega, V_{GS}=12V$		87		ns
Rise Time	t_r			30		
Turn-off Delay Time	$t_{d(off)}$			205		
Fall Time	t_f			15		
Gate Charge Characteristics						
Gate to Source Charge	Q_{gs}	$V_{DD}=400V, I_D=40A$ $V_{GS}=0$ to 10V		66		nC
Gate to Drain Charge	Q_{gd}			226		
Gate Charge Total	Q_g			408		
Gate Plateau Voltage	$V_{plateau}$			7.8		V
Reverse Diode Characteristics						
Drain-Source Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_{SD}=40A$		0.85	1.1	V
Reverse Recovery Time	t_{rr}	$V_R=400V, I_F=40A$ $dI_F/dt=100A/\mu s$		238		ns
Reverse Recovery Charge	Q_{rr}			3.2		μC
Peak Reverse Recovery Current	I_{rrm}			22		A

Note:

- $C_{O(er)}$ is a fixed capacitance that gives the same stored energy as C_{OSS} while V_{DS} is rising from 0 to 400V
- $C_{O(tr)}$ is a fixed capacitance that gives the same charging time as C_{OSS} while V_{DS} is rising from 0 to 400V



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